

Atty Docket No.: JCLA8479

Serial No.: 10/033,749

**FOR THE CLAIMS**

Claim 1. (Currently amended) A resilient and rugged probe, to measure an on-wafer signal, the probe comprising:

a metal probe tip;

a resilient ~~soft~~ multi-layered dielectric substrate, ~~coupled to the metal probe tip;~~

a planar transmission structure, coupled to the metal probe tip and attached onto the resilient ~~soft~~ multi-layered dielectric substrate, wherein the metal probe tip extends out from the planar transmission structure without being attached to the resilient multi-layered dielectric substrate; and

a fixed end, coupled to the resilient ~~soft~~ multi-layered dielectric substrate and the planar transmission structure.

Claim 2. (Currently cancelled).

Claim 3. (Original) The resilient and rugged probe according to claim 1, wherein the metal probe tip is used to probe the on-wafer signal.

Claim 4. (Currently amended) The resilient and rugged probe according to claim 1, wherein the metal probe tip is able to rotate around an axis with a first ~~limited~~ angle.

Claim 5. (Currently amended) The resilient and rugged probe according to claim 1, wherein the metal probe tip is able to lift and dive with a second angle.

Claim 6. (Original) The resilient and rugged probe according to claim 1, wherein the fixed end is used to support and hold the probe.

Claim 7. (Original) The resilient and rugged probe according to claim 1, wherein the fixed end is used as a transmission structure converter of the probe to connect the planar transmission structure to a coaxial transmission structure.

Claim 8. (Currently amended) A resilient and rugged probe, used to measure a signal of a substrate, comprising:

a probe tip;

a planar transmission structure, coupled to the probe tip; and

a multi-layered dielectric material, coupled to the planar transmission structure, wherein and the probe tip extends out from the planar transmission structure without being attached to the multi-layered dielectric material, and wherein the multi-layered dielectric material allows a device

Atty Docket No.: JCLA8479

Serial No.: 10/033,749

to be embedded therein.

Claim 9. (Original) The resilient and rugged probe according to claim 8, wherein the device includes a multi-layered microwave circuit.

Claim 10. (Original) The resilient and rugged probe according to claim 8, wherein the device includes a vertical connector.

Claim 11. (Original) The resilient and rugged probe according to claim 8, wherein the device includes a matching circuit device.

Claim 12. (Currently cancelled).

Claim 13. (Currently amended) The resilient and rugged probe according to claim 8, wherein the probe tip is used to probe the on-wafer-signal of the substrate.

Claim 14. (Currently amended) The resilient and rugged probe according to claim 8, wherein the probe tip canis able to rotate about an axis with a firstlimited angle.

Claim 15. (Currently amended) The resilient and rugged probe according to claim 8, wherein the probe tip is able to lift and dive with a second angle.

Claims 16-23. (Currently cancelled).

**Atty Docket No.: JCLA8479**

**Serial No.: 10/033,749**

**FOR THE DRAWINGS**

Please add new Figs 1A, 1C, and 5B, and amend Figs. 1 and 5 as shown in the attached sheets. Approval of the drawing change is requested. Formal drawings will be submitted when the application is allowed.